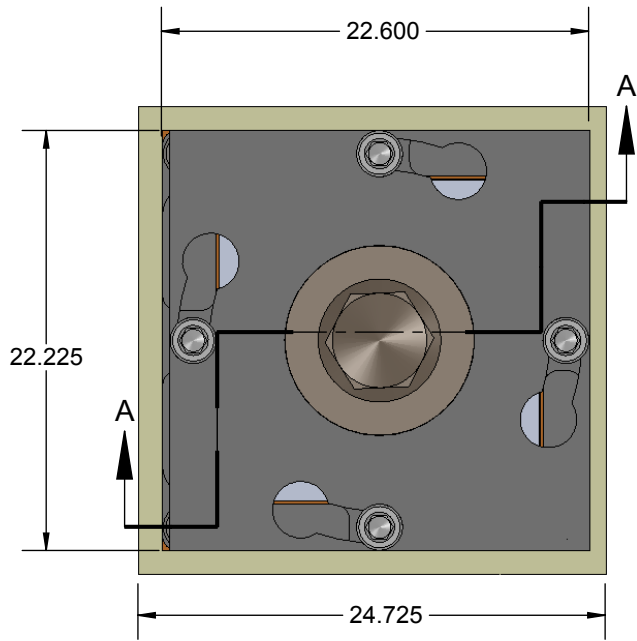


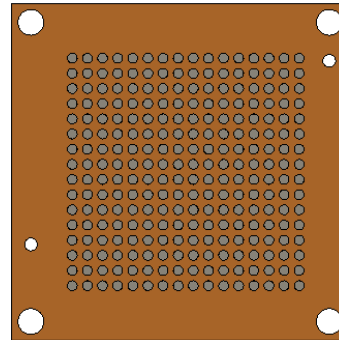
GHz BGA Socket - Direct mount, solderless

Features

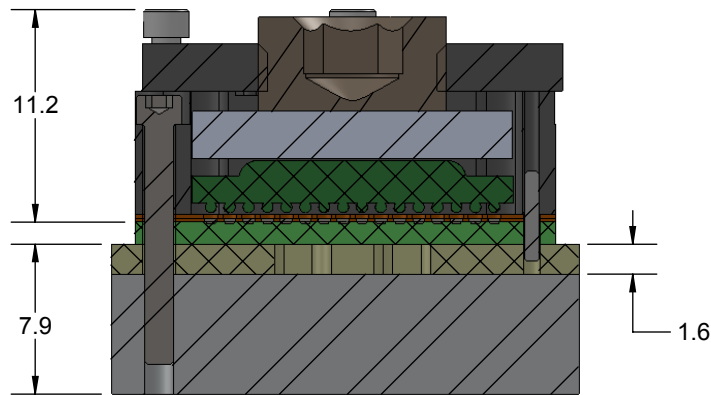
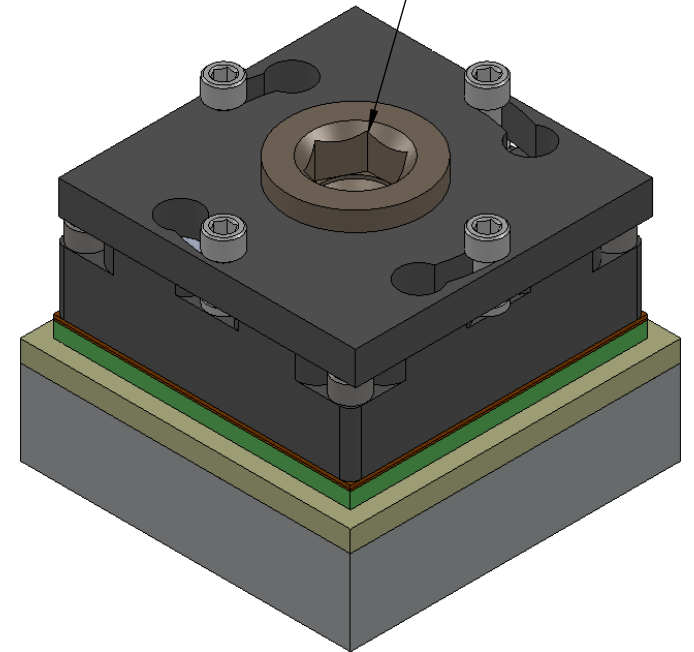
- Directly mounts to target PCB (needs tooling holes) with hardware
- High speed, reliable connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid
- Operating temperature range -55C to +160C



RECOMMENDED TORQUE: 45 - 57 N-cm [4-5 lbf-in]



GT elastomer




SECTION A-A

Description: GT Socket for 17x17mm 1mm pitch BGA256

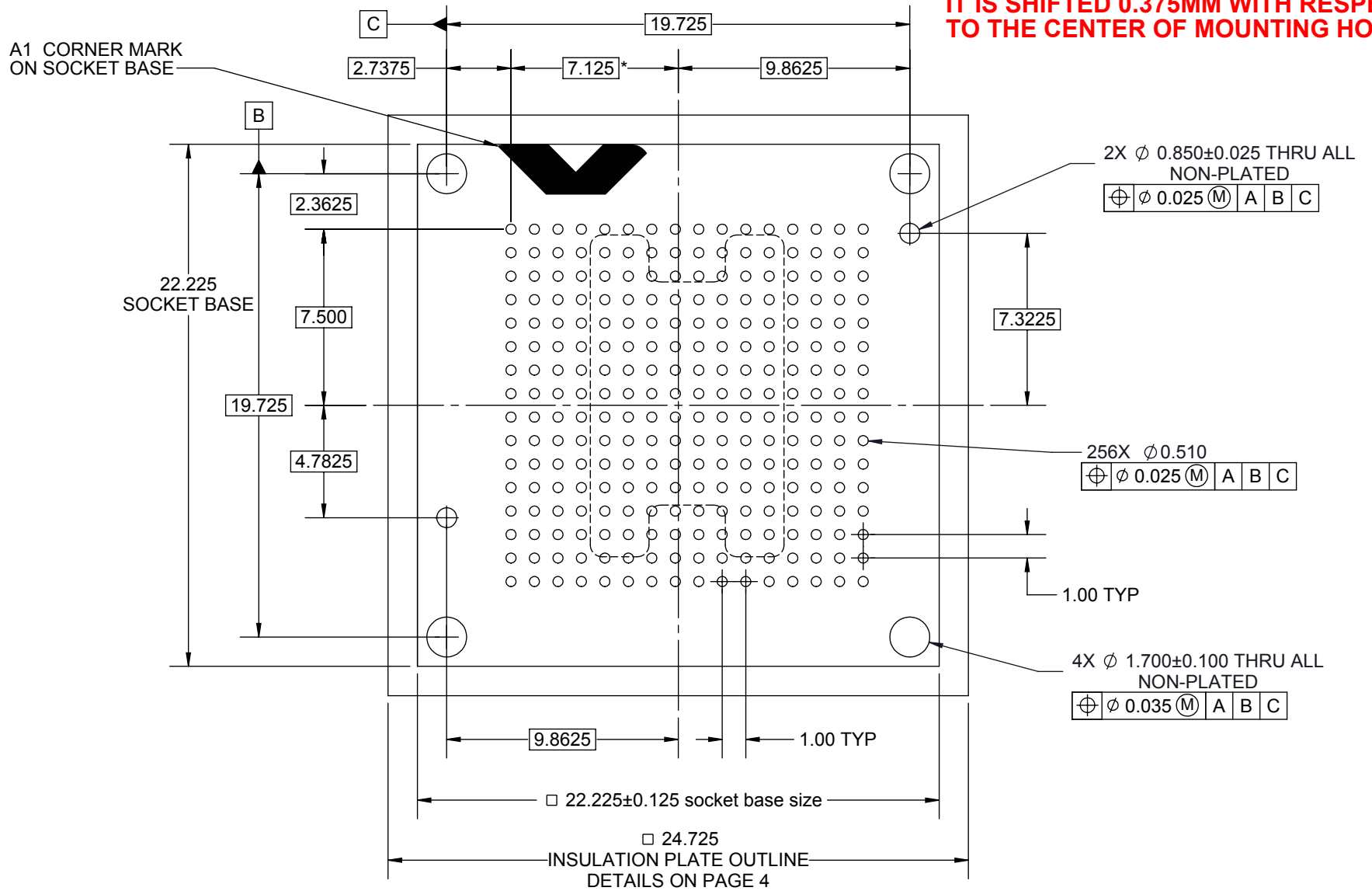
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.0254\text{mm}$ [± 0.001 "]. Pitches (from true position) $\pm 0.0762\text{mm}$ [± 0.003 "], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.127\text{mm}$ [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

 GT-BGA-2006 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 23.54	STATUS: Released ENG: S. Huang FILE: GT-BGA-2006 Dwg	SHEET: 1 OF 4 DRAWN BY: D. Hauer DATE: 9/25/14	REV. A SCALE: 5:2

DATUM A IS TOP SIDE OF BOARD

**NOTE: PAD LAYOUT IS NOT CENTERED
IT IS SHIFTED 0.375MM WITH RESPECT
TO THE CENTER OF MOUNTING HOLES**



Description: Recommended PCB Layout

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.


Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

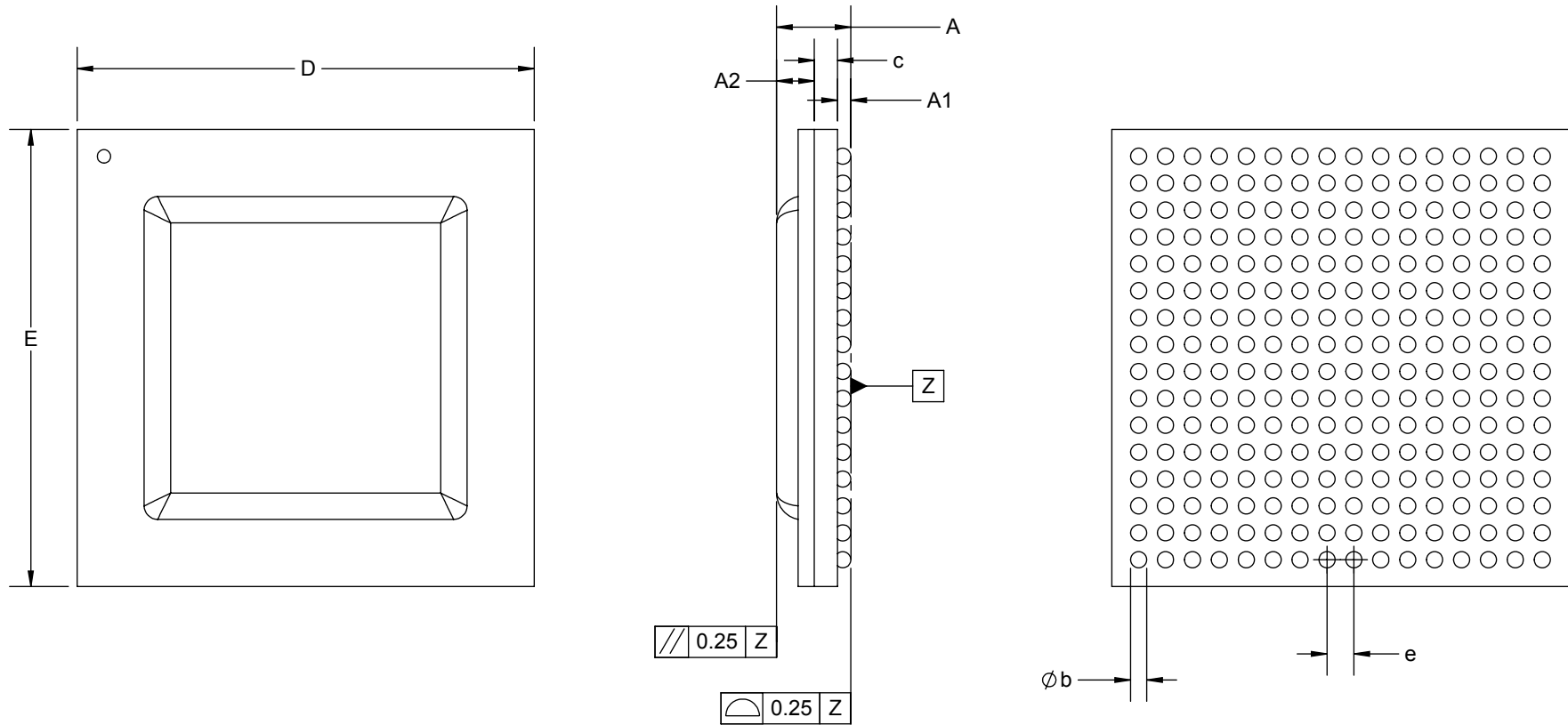
Target PCB Recommendations

Total Thickness: 1.6mm min.

Plating: Gold Immersion, Silver Immersion or Solder

PCB Pad Height: same or higher than solder mask

 <p>GT-BGA-2006 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	<p>Material: N/A Finish: N/A Weight: 23.54</p>	<p>STATUS: Released ENG: S. Huang FILE: GT-BGA-2006 Dwg</p>	<p>SHEET: 2 OF 4 DRAWN BY: D. Hauer DATE: 9/25/14</p>	<p>REV. A SCALE: 4:1</p>



1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.


DIM	MIN	NOM	MAX
A	2.5	2.76	3.02
A1	0.4	0.5	0.6
A2	2.1	2.26	2.42
b	0.5	0.6	0.7
c	0.76	0.86	0.96
D	16.8		17.2
E	16.8		17.2
e	1.0		

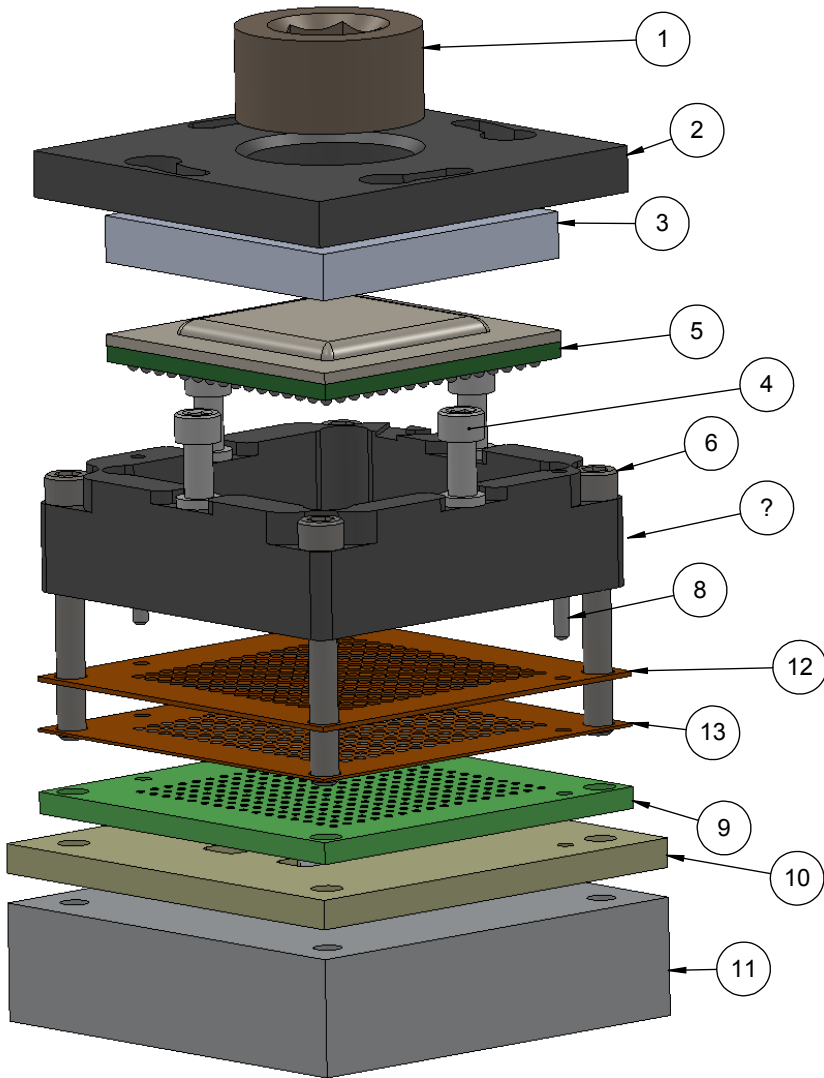
Array: 16x16

Description: Compatible Device

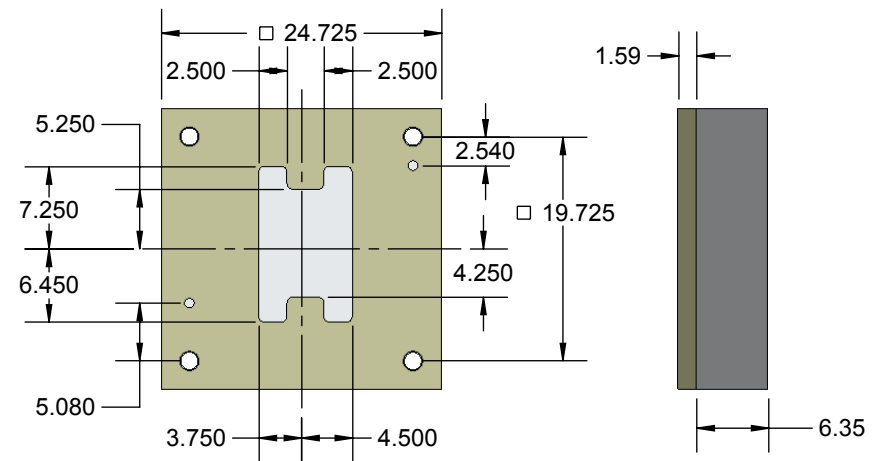
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

 GT-BGA-2006 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 23.54	STATUS: Released	SHEET: 3 OF 4	REV. A
		ENG: S. Huang	DRAWN BY: D. Hauer	SCALE: 4:1
		FILE: GT-BGA-2006 Dwg	DATE: 9/25/14	



ITEM NO.	DESCRIPTION	Material
1	Compression Screw	Alumium Alloy
2	Socket Lid	Aluminum Alloy
3	Compression Plate	Aluminum Alloy
4	Shoulder Screw	Stainless Steel
5	Compatible BGA	High Temp FR4
6	Mounting Screw	Stainless Steel
7	Socket Base	Aluminum Alloy
8	Dowel Pin	Stainless Steel
9	Target PCB	High Temp FR4
10	Custom Insulation Plate	High Temp FR4
11	Backing Plate	Aluminum Alloy
12	Ball Guide	Kapton Polyimide/Cirlex
13	GT Elastomer 17x17mm IC 1mm pitch 16x16 array	Conductive Elastomer




Description: Socket, Backing Plate Detail

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

INSULATION AND BACKING PLATE DETAIL

 GT-BGA-2006 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 23.54	STATUS: Released ENG: S. Huang FILE: GT-BGA-2006 Dwg	SHEET: 4 OF 4 DRAWN BY: D. Hauer DATE: 9/25/14	REV. A SCALE: 5:2
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